



EVG Technology Day

in HSINCHU, Taiwan
March 29, 2023

Schedule

March 29, 2023

08:00 - 16:30 hrs

EVG Technology Day

Location

Ambassador Hotel Hsinchu,
188, Section 2, Zhonghua Road,
Hsinchu 30060, Taiwan

EVG Speaker

Paul Lindner

Dr. Thomas Uhrmann

Cindy Lee

Eric Hung

Dr. Ksenija Varga

Andrea Kneidinger

Christine Thanner

Guest Speaker



Dr. Mike Chang



In cooperation with



Register

For more information
and to register for free:

www.EVGroup.com/events

AI, Augmented Reality, 5G and Autonomous Driving: Addressing the Manufacturing Challenges of next gen Devices

Agenda

08:00	Registration & Breakfast with EVG - Our Experts will be Available for a Coffee and Chat!
09:00	Welcome Remarks by Paul Lindner, Executive Technology Director
Wafer Bonding Technologies Enabling 3DIC and Next Gen Scaled Devices	
09:10	Hybrid Bonding - A Game Changer for 3D SOCs, Image Sensors and Artificial Intelligence
09:35	High-Precision Metrology System Driving Heterogeneous Integration Roadmap
09:55	Keynote: Ultra Low Temperature Wafer Hybrid Bonding and Advanced Package Capacity in ITRI
10:15	Coffee Break & Poster Session
EVG Latest Technology Innovations	
10:35	EVG BONDSCALE® - Wafer Bonding enabling the continuation of Moore's Law
10:55	EVG NanoCleave™ - Novel IR Laser Release for Next gen 3D Stacked Devices
11:25	Keynote: Yole Développement
11:45	Invited Lunch
Die-to-Wafer Chiplet Integration	
12:45	Invited Talk: ASMPT - Fine-pitch Interconnect Technologies for 2.5D and 3D Integration
13:10	Die to Wafer Fusion and Hybrid Bonding: direct Placement and Collective
Advanced Packaging / FOWLP / SiPs	
13:35	DPSS Laser Debonding for 3DIC and Fan-Out Wafer Level Packaging
14:00	LITHOSCALE® Maskless Lithography for High-Volume Manufacturing
14:30	Coffee Break & Poster Session
AR / VR and Optics Manufacturing - Session	
14:50	Nanoimprint Lithography - Ideal Manufacturing Technology for Advanced Photonics Devices, Metalens, DOE and Optical Waveguides
15:05	Wafer Level Optics Manufacturing - from Lab to HVM
15:25	MicroLED - Transfer Processes enabled by Wafer Bonding
GaN SiC Power Semiconductors for EV - Key Enabling Manufacturing Processes	
15:40	ComBond® - Conductive and Oxide Free Wafer Level Bonding
16:00	Lucky Draw & Closing Remarks

